



Material Content Data Sheet



Sales Product Name				BGSX 28MA18 E6327		Issued		19. January 2018	
MA#				MA001479398					
Package				PG-ATSLP-18-4		Weight*		6.41 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.223	3.49	3.49	34859	34859	
bumps	noble metal	silver	7440-22-4	0.000	0.00		33		
	non noble metal	tin	7440-31-5	0.009	0.14		1396		
encapsulation	non noble metal	copper	7440-50-8	0.025	0.39	0.53	3896	5325	
	organic material	carbon black	1333-86-4	0.023	0.36		3642		
	plastics	epoxy resin	-	0.677	10.56		105607		
leadfinish	inorganic material	silicondioxide	60676-86-0	3.967	61.92	72.84	619078	728327	
	noble metal	gold	7440-57-5	0.059	0.92		9211		
substrate	non noble metal	nickel	7440-02-0	0.067	1.05	1.97	10505	19716	
	organic material	carbon black	1333-86-4	0.002	0.03		310		
	plastics	epoxy resin	-	0.078	1.21		12102		
	non noble metal	copper	7440-50-8	0.505	7.88		78801		
ubm	inorganic material	silicondioxide	60676-86-0	0.583	9.10	18.22	91023	182236	
	non noble metal	copper	7440-50-8	0.000	0.00		25		
	non noble metal	nickel	7440-02-0	0.002	0.03		346		
	non noble metal	titanium	7440-32-6	0.000	0.00		9		
	non noble metal	tungsten	7440-33-7	0.000	0.00	0.03	9	389	
solder resists	inorganic material	silicondioxide	60676-86-0	0.040	0.62		6194		
	inorganic material	bariumsulfate	7727-43-7	0.040	0.63		6267		
	plastics	acrylic resin	-	0.107	1.67	2.92	16687	29148	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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